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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

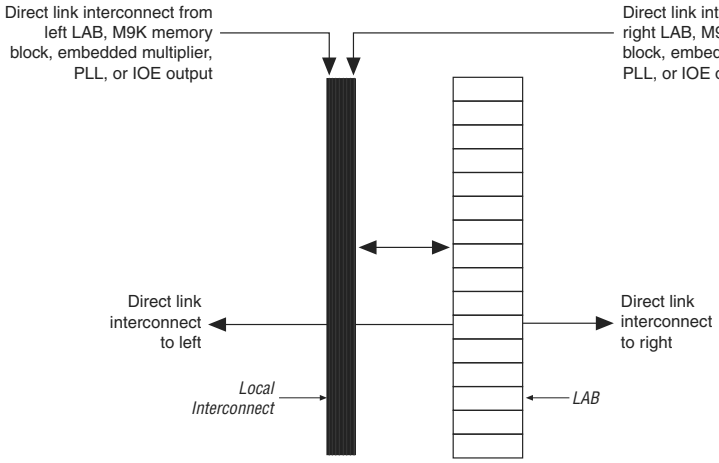
Details	
Product Status	Active
Number of LABs/CLBs	3491
Number of Logic Elements/Cells	55856
Total RAM Bits	2396160
Number of I/O	324
Number of Gates	-
Voltage - Supply	1.15V ~ 1.25V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	484-BGA
Supplier Device Package	484-FBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep4ce55f23c8n

LAB Interconnects

The LAB local interconnect is driven by column and row interconnects and LE outputs in the same LAB. Neighboring LABs, phase-locked loops (PLLs), M9K RAM blocks, and embedded multipliers from the left and right can also drive the local interconnect of a LAB through the direct link connection. The direct link connection feature minimizes the use of row and column interconnects, providing higher performance and flexibility. Each LE can drive up to 48 LEs through fast local and direct link interconnects.

Figure 2–5 shows the direct link connection.

Figure 2–5. Cyclone IV Device Direct Link Connection



LAB Control Signals

Each LAB contains dedicated logic for driving control signals to its LEs. The control signals include:

- Two clocks
- Two clock enables
- Two asynchronous clears
- One synchronous clear
- One synchronous load

You can use up to eight control signals at a time. Register packing and synchronous load cannot be used simultaneously.

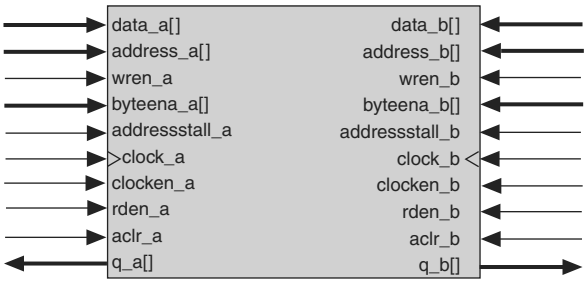
Each LAB can have up to four non-global control signals. You can use additional LAB control signals as long as they are global signals.

Synchronous clear and load signals are useful for implementing counters and other functions. The synchronous clear and synchronous load signals are LAB-wide signals that affect all registers in the LAB.

True Dual-Port Mode

True dual-port mode supports any combination of two-port operations: two reads, two writes, or one read and one write, at two different clock frequencies. Figure 3–10 shows Cyclone IV devices true dual-port memory configuration.

Figure 3–10. Cyclone IV Devices True Dual-Port Memory *(1)*



Note to Figure 3–10:

(1) True dual-port memory supports input or output clock mode in addition to the independent clock mode shown.

1 The widest bit configuration of the M9K blocks in true dual-port mode is 512 × 16-bit (18-bit with parity).

Table 3–4 lists the possible M9K block mixed-port width configurations.

Table 3–4. Cyclone IV Devices M9K Block Mixed-Width Configurations (True Dual-Port Mode)

Read Port	Write Port						
	8192 × 1	4096 × 2	2048 × 4	1024 × 8	512 × 16	1024 × 9	512 × 18
8192 × 1	v	v	v	v	v	—	—
4096 × 2	v	v	v	v	v	—	—
2048 × 4	v	v	v	v	v	—	—
1024 × 8	v	v	v	v	v	—	—
512 × 16	v	v	v	v	v	—	—
1024 × 9	—	—	—	—	—	v	v
512 × 18	—	—	—	—	—	v	v

In true dual-port mode, M9K memory blocks support separate `wren` and `rden` signals. You can save power by keeping the `rden` signal low (inactive) when not reading. Read-during-write operations to the same address can either output "New Data" at that location or "Old Data". To choose the desired behavior, set the **Read-During-Write** option to either **New Data** or **Old Data** in the RAM MegaWizard Plug-In Manager in the Quartus II software. For more information about this behavior, refer to "Read-During-Write Operations" on page 3–15.

Table 5–10. Loop Filter Control of High Frequency Capacitor

LFC[1]	LFC[0]	Setting (Decimal)
0	0	0
0	1	1
1	1	3

Bypassing a PLL Counter

Bypassing a PLL counter results in a divide (N, C0 to C4 counters) factor of one.

Table 5–11 lists the settings for bypassing the counters in PLLs of Cyclone IV devices.

Table 5–11. PLL Counter Settings

PLL Scan Chain Bits [0..8] Settings									Description
LSB								MSB	
X	X	X	X	X	X	X	X	1 (1)	PLL counter bypassed
X	X	X	X	X	X	X	X	0 (1)	PLL counter not bypassed

Note to Table 5–11:

(1) Bypass bit.

To bypass any of the PLL counters, set the bypass bit to 1. The values on the other bits are then ignored.

Dynamic Phase Shifting

The dynamic phase shifting feature allows the output phase of individual PLL outputs to be dynamically adjusted relative to each other and the reference clock without sending serial data through the scan chain of the corresponding PLL. This feature simplifies the interface and allows you to quickly adjust t_{CO} delays by changing output clock phase shift in real time. This is achieved by incrementing or decrementing the VCO phase-tap selection to a given C counter or to the M counter. The phase is shifted by 1/8 the VCO frequency at a time. The output clocks are active during this phase reconfiguration process.

Table 5–12 lists the control signals that are used for dynamic phase shifting.

Table 5–12. Dynamic Phase Shifting Control Signals (Part 1 of 2)

Signal Name	Description	Source	Destination
`phasecounterselect[2..0]`	Counter Select. Three bits decoded to select either the M or one of the C counters for phase adjustment. One address map to select all C counters. This signal is registered in the PLL on the rising edge of `scanclk`.	Logic array or I/O pins	PLL reconfiguration circuit
`phaseupdown`	Selects dynamic phase shift direction; 1= UP, 0 = DOWN. Signal is registered in the PLL on the rising edge of `scanclk`.	Logic array or I/O pins	PLL reconfiguration circuit
`phasestep`	Logic high enables dynamic phase shifting.	Logic array or I/O pins	PLL reconfiguration circuit

Each Cyclone IV I/O bank has a VREF bus to accommodate voltage-referenced I/O standards. Each VREF pin is the reference source for its V_{REF} group. If you use a V_{REF} group for voltage-referenced I/O standards, connect the VREF pin for that group to the appropriate voltage level. If you do not use all the V_{REF} groups in the I/O bank for voltage-referenced I/O standards, you can use the VREF pin in the unused voltage-referenced groups as regular I/O pins. For example, if you have SSTL-2 Class I input pins in I/O bank 1 and they are all placed in the VREFB1N[0] group, VREFB1N[0] must be powered with 1.25 V, and the remaining VREFB1N[1..3] pins (if available) are used as I/O pins. If multiple V_{REF} groups are used in the same I/O bank, the VREF pins must all be powered by the same voltage level because the VREF pins are shorted together within the same I/O bank.

1 When VREF pins are used as regular I/Os, they have higher pin capacitance than regular user I/O pins. This has an impact on the timing if the pins are used as inputs and outputs.

f For more information about VREF pin capacitance, refer to the pin capacitance section in the Cyclone IV Device Datasheet chapter.

f For information about how to identify V_{REF} groups, refer to the Cyclone IV **Device Pin-Out** files or the **Quartus II Pin Planner** tool.

Table 6–4 and Table 6–5 summarize the number of VREF pins in each I/O bank for the Cyclone IV device family.

Table 6–4. Number of VREF Pins Per I/O Bank for Cyclone IV E Devices (Part 1 of 2)

Device	EP4CE6			EP4CE10			EP4CE15						EP4CE22			EP4CE30			EP4CE40				EP4CE55			EP4CE75			EP4CE115	
I/O Bank *(1)*	144-EQPF	256-UBGA	256-FBGA	144-EQPF	256-UBGA	256-FBGA	144-EQPF	164-MBGA	256-MBGA	256-UBGA	256-FBGA	484-FBGA	144-EQPF	256-UBGA	256-FBGA	324-FBGA	484-FBGA	780-FBGA	324-FBGA	484-UBGA	484-FBGA	780-FBGA	484-UBGA	484-FBGA	780-FBGA	484-UBGA	484-FBGA	780-FBGA	484-FBGA	780-FBGA
1	1	1	1	1	1	1	2	2	2	2	2	2	1	1	1	4	4	4	4	4	4	4	2	2	2	3	3	3	3	3
2	1	1	1	1	1	1	2	2	2	2	2	2	1	1	1	4	4	4	4	4	4	4	2	2	2	3	3	3	3	3
3	1	1	1	1	1	1	2	2	2	2	2	2	1	1	1	4	4	4	4	4	4	4	2	2	2	3	3	3	3	3
4	1	1	1	1	1	1	2	2	2	2	2	2	1	1	1	4	4	4	4	4	4	4	2	2	2	3	3	3	3	3
5	1	1	1	1	1	1	2	2	2	2	2	2	1	1	1	4	4	4	4	4	4	4	2	2	2	3	3	3	3	3
6	1	1	1	1	1	1	2	2	2	2	2	2	1	1	1	4	4	4	4	4	4	4	2	2	2	3	3	3	3	3
7	1	1	1	1	1	1	2	2	2	2	2	2	1	1	1	4	4	4	4	4	4	4	2	2	2	3	3	3	3	3

Figure 7–3 shows the location and numbering of the DQS, DQ, or CQ# pins in I/O banks of the Cyclone IV GX device in the 324-pin FBGA package only.

Figure 7–3. DQS, CQ, or CQ# Pins for Cyclone IV GX Devices in the 324-Pin FBGA Package

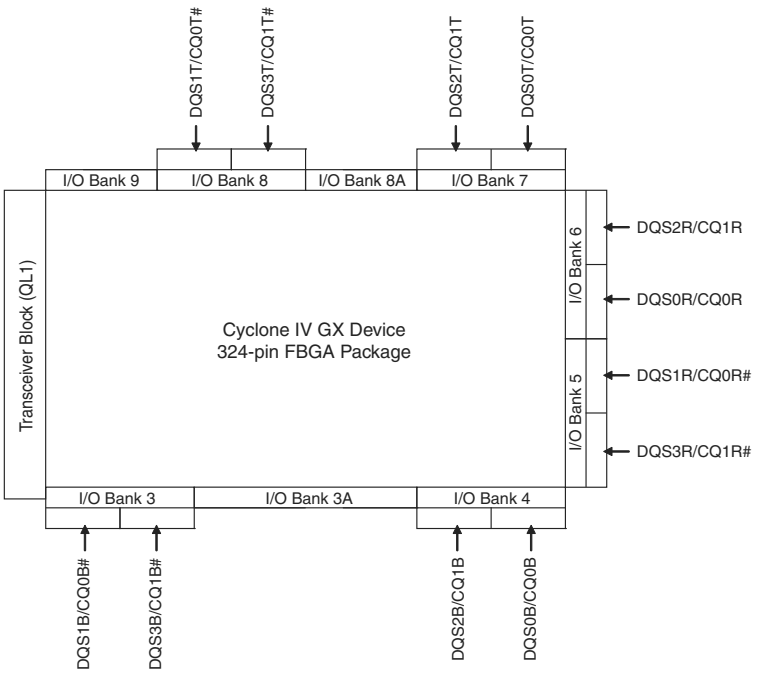
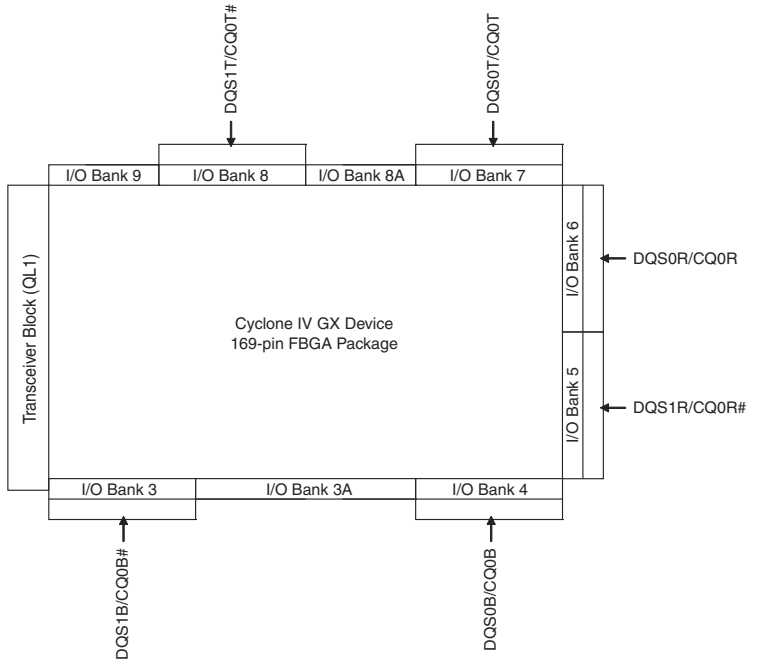


Figure 7–4 shows the location and numbering of the DQS, DQ, or CQ# pins in I/O banks of the Cyclone IV GX device in the 169-pin FBGA package.

Figure 7–4. DQS, CQ, or CQ# Pins for Cyclone IV GX Devices in the 169-Pin FBGA Package



In Cyclone IV devices, the DM pins are preassigned in the device pinouts. The Quartus II Fitter treats the DQ and DM pins in a DQS group equally for placement purposes. The preassigned DQ and DM pins are the preferred pins to use.

Some DDR2 SDRAM and DDR SDRAM devices support error correction coding (ECC), a method of detecting and automatically correcting errors in data transmission. In 72-bit DDR2 or DDR SDRAM, there are eight ECC pins and 64 data pins. Connect the DDR2 and DDR SDRAM ECC pins to a separate DQS or DQ group in Cyclone IV devices. The memory controller needs additional logic to encode and decode the ECC data.

Address and Control/Command Pins

The address signals and the control or command signals are typically sent at a single data rate. You can use any of the user I/O pins on all I/O banks of Cyclone IV devices to generate the address and control or command signals to the memory device.

1 Cyclone IV devices do not support QDR II SRAM in the burst length of two.

Memory Clock Pins

In DDR2 and DDR SDRAM memory interfaces, the memory clock signals (CK and CK#) are used to capture the address signals and the control or command signals. Similarly, QDR II SRAM devices use the write clocks (K and K#) to capture the address and command signals. The CK/CK# and K/K# signals are generated to resemble the write-data strobe using the DDIO registers in Cyclone IV devices.

1 CK/CK# pins must be placed on differential I/O pins (DIFFIO in Pin Planner) and in the same bank or on the same side as the data pins. You can use either side of the device for wraparound interfaces. As seen in the Pin Planner Pad View, CK0 cannot be located in the same row and column pad group as any of the interfacing DQ pins.

f For more information about memory clock pin placement, refer to Volume 2: Device, Pin, and Board Layout Guidelines of the External Memory Interface Handbook.

Cyclone IV Devices Memory Interfaces Features

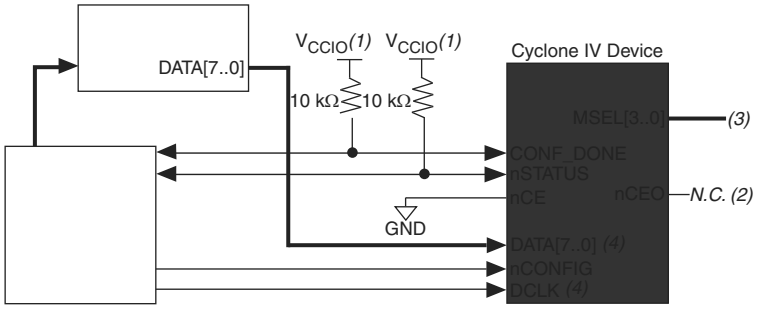
This section discusses Cyclone IV memory interfaces, including DDR input registers, DDR output registers, OCT, and phase-lock loops (PLLs).

DDR Input Registers

The DDR input registers are implemented with three internal logic element (LE) registers for every DQ pin. These LE registers are located in the logic array block (LAB) adjacent to the DDR input pin.

the device, must be stored in the external host device. Figure 8–19 shows the configuration interface connections between the Cyclone IV devices and an external device for single-device configuration.

Figure 8–19. Single-Device FPP Configuration Using an External Host



Notes to Figure 8–19:

(1) Connect the pull-up resistor to a supply that provides an acceptable input signal for the device. V_{CC} must be high enough to meet the V_{IH} specification of the I/O on the device and the external host.

(2) The nCEO pin is left unconnected or used as a user I/O pin when it does not feed the nCE pin of another device.

(3) The MSEL pin settings vary for different configuration voltage standards and POR time. To connect the MSEL pins, refer to Table 8–4 on page 8–8 and Table 8–5 on page 8–9. Connect the MSEL pins directly to V_{CCA} or GND.

(4) All I/O inputs must maintain a maximum AC voltage of 4.1 V. DATA[7..0] and DCLK must fit the maximum overshoot outlined in Equation 8–1 on page 8–5.

After nSTATUS is released, the device is ready to receive configuration data and the configuration stage begins. When nSTATUS is pulled high, the external host device places the configuration data one byte at a time on the DATA[7..0] pins.

Cyclone IV devices receive configuration data on the DATA[7..0] pins and the clock is received on the DCLK pin. Data is latched into the device on the rising edge of DCLK. Data is continuously clocked into the target device until CONF_DONE goes high. The CONF_DONE pin goes high one byte early in FPP configuration mode. The last byte is required for serial configuration (AS and PS) modes.

1 Two DCLK falling edges are required after CONF_DONE goes high to begin initialization of the device.

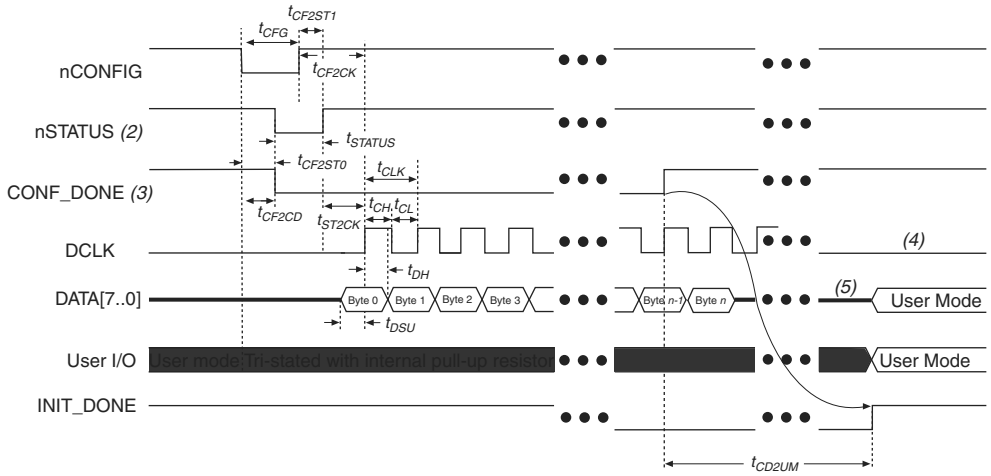
Supplying a clock on CLKUSR does not affect the configuration process. After the CONF_DONE pin goes high, CLKUSR is enabled after the time specified as t_{CD2CU}. After this time period elapses, Cyclone IV devices require 3,192 clock cycles to initialize properly and enter user mode. For more information about the supported CLKUSR f_{MAX} value for Cyclone IV devices, refer to Table 8–13 on page 8–44.

The INIT_DONE pin is released and pulled high when initialization is complete. The external host device must be able to detect this low-to-high transition, which signals the device has entered user mode. When initialization is complete, the device enters user mode. In user mode, the user I/O pins no longer have weak pull-up resistors and function as assigned in your design.

FPP Configuration Timing

Figure 8–22 shows the timing waveform for the FPP configuration when using an external host.

Figure 8–22. FPP Configuration Timing Waveform (1)



Notes to Figure 8–22:

(1) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic-high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.

(2) After power up, the Cyclone IV device holds nSTATUS low during POR delay.

(3) After power up, before and during configuration, CONF_DONE is low.

(4) Do not leave DCLK floating after configuration. It must be driven high or low, whichever is more convenient.

(5) DATA[7..0] is available as a user I/O pin after configuration; the state of the pin depends on the dual-purpose pin settings.

Table 8–13 lists the FPP configuration timing parameters for Cyclone IV devices.

Table 8–13. FPP Timing Parameters for Cyclone IV Devices (Part 1 of 2)

Symbol	Parameter	Minimum		Maximum		Unit
		Cyclone IV (1)	Cyclone IV E (2)	Cyclone IV (1)	Cyclone IV E (2)	
t_{CF2CD}	nCONFIG low to CONF_DONE low	—		500		ns
t_{CF2ST0}	nCONFIG low to nSTATUS low	—		500		ns
t_{CFG}	nCONFIG low pulse width	500		—		ns
t_{STATUS}	nSTATUS low pulse width	45		230 (3)		µs
t_{CF2ST1}	nCONFIG high to nSTATUS high	—		230 (4)		µs
t_{CF2CK}	nCONFIG high to first rising edge on DCLK	230 (3)		—		µs

- In AP configuration scheme, the only way to re-engage the AP controller is to issue the ACTIVE_ENGAGE instruction. In this case, asserting the nCONFIG pin does not re-engage either active controller.

ACTIVE_ENGAGE

The ACTIVE_ENGAGE instruction allows you to re-engage a disengaged active controller. You can issue this instruction any time during configuration or user mode to re-engage an already disengaged active controller, as well as trigger reconfiguration of the Cyclone IV device in the active configuration scheme.

The ACTIVE_ENGAGE instruction functions as the PULSE_NCONFIG instruction when the device is in the PS or FPP configuration schemes. The nCONFIG pin is disabled when the ACTIVE_ENGAGE instruction is issued.

1 Altera does not recommend using the ACTIVE_ENGAGE instruction, but it is provided as a fail-safe instruction for re-engaging the active configuration controller (AS and AP).

Overriding the Internal Oscillator

This feature allows you to override the internal oscillator during the active configuration scheme. The AS and AP configuration controllers use the internal oscillator as the clock source. You can change the clock source to CLKUSR through the JTAG instruction.

The EN_ACTIVE_CLK and DIS_ACTIVE_CLK JTAG instructions toggle on or off whether or not the active clock is sourced from the CLKUSR pin or the internal configuration oscillator. To source the active clock from the CLKUSR pin, issue the EN_ACTIVE_CLK instruction. This causes the CLKUSR pin to become the active clock source. When using the EN_ACTIVE_CLK instruction, you must enable the internal oscillator for the clock change to occur. By default, the configuration oscillator is disabled after configuration and initialization is complete as well as the device has entered user mode.

However, the internal oscillator is enabled in user mode by any of the following conditions:

- A reconfiguration event (for example, driving the nCONFIG pin to go low)
- Remote update is enabled
- Error detection is enabled

1 When using the EN_ACTIVE_CLK and DIS_ACTIVE_CLK JTAG instructions to override the internal oscillator, you must clock the CLKUSR pin at two times the expected DCLK frequency. The CLKUSR pin allows a maximum frequency of 40 MHz (40 MHz DCLK).

Normally, a test instrument uses the CLKUSR pin when it wants to drive its own clock to control the AS state machine.

To revert the clock source back to the configuration oscillator, issue the DIS_ACTIVE_CLK instruction. After you issue the DIS_ACTIVE_CLK instruction, you must continue to clock the CLKUSR pin for 10 clock cycles. Otherwise, even toggling the nCONFIG pin does not revert the clock source and reconfiguration does not occur. A POR reverts the clock source back to the configuration oscillator. Toggling the nCONFIG pin or driving the JTAG state machine to reset state does not revert the clock source.

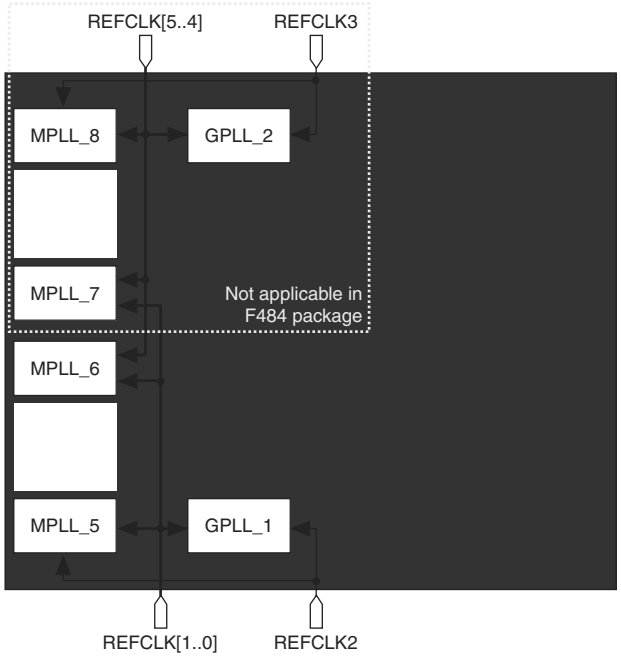
Table 8–19. Configuration Pin Summary for Cyclone IV E Devices (Part 2 of 3)

Bank	Description	Input/Output	Dedicated	Powered By	Configuration Mode
1	DATA[0] *(1), (2)*	Input	—	V_{CCIO}	PS, FPP, AS
		Bidirectional		V_{CCIO}	AP
1	DATA[1] *(2)*/ASDO *(1)*	Input	—	V_{CCIO}	FPP
		Output		V_{CCIO}	AS
		Bidirectional		V_{CCIO}	AP
8	DATA[7..2] *(2)*	Input	—	V_{CCIO}	FPP
		Bidirectional		V_{CCIO}	AP
8	DATA[15..8] *(2)*	Bidirectional	—	V_{CCIO}	AP
6	INIT_DONE	Output	—	Pull-up	Optional, all modes
1	nSTATUS	Bidirectional	Yes	Pull-up	All modes
1	nCE	Input	Yes	V_{CCIO}	All modes
1	DCLK *(1), (2)*	Input	Yes	V_{CCIO}	PS, FPP
		Output	—	V_{CCIO}	AS, AP
6	CONF_DONE	Bidirectional	Yes	Pull-up	All modes
1	TDI	Input	Yes	V_{CCIO}	JTAG
1	TMS	Input	Yes	V_{CCIO}	JTAG
1	TCK	Input	Yes	V_{CCIO}	JTAG
1	nCONFIG	Input	Yes	V_{CCIO}	All modes
6	CLKUSR	Input	—	V_{CCIO}	Optional
6	nCEO	Output	—	V_{CCIO}	Optional, all modes
6	MSEL[]	Input	Yes	V_{CCINT}	All modes
1	TDO	Output	Yes	V_{CCIO}	JTAG
7	PADD[14..0]	Output	—	V_{CCIO}	AP
8	PADD[19..15]	Output	—	V_{CCIO}	AP
6	PADD[23..20]	Output	—	V_{CCIO}	AP
1	nRESET	Output	—	V_{CCIO}	AP
6	nAVD	Output	—	V_{CCIO}	AP
6	nOE	Output	—	V_{CCIO}	AP
6	nWE	Output	—	V_{CCIO}	AP
5	DEV_OE	Input	—	V_{CCIO}	Optional, AP

Table 8–28. Document Revision History (Part 2 of 2)

Date	Version	Changes
July 2010	1.2	Updated for the Quartus II software 10.0 release: ■ Updated "Power-On Reset (POR) Circuit", "Configuration and JTAG Pin I/O Requirements", and "Reset" sections. ■ Updated Figure 8–10. ■ Updated Table 8–16 and Table 8–17.
February 2010	1.1	Updated for the Quartus II software 9.1 SP1 release: ■ Added "Overriding the Internal Oscillator" and "AP Configuration (Supported Flash Memories)" sections. ■ Updated "JTAG Instructions" section. ■ Added Table 8–6. ■ Updated Table 8–2, Table 8–3, Table 8–4, Table 8–6, Table 8–11, Table 8–13, Table 8–14, Table 8–15, and Table 8–18. ■ Updated Figure 8–4, Figure 8–5, Figure 8–6, Figure 8–13, Figure 8–14, Figure 8–15, Figure 8–17, Figure 8–18, Figure 8–23, Figure 8–24, Figure 8–25, Figure 8–26, Figure 8–27, Figure 8–28, and Figure 8–29.
November 2009	1.0	Initial release.

Figure 1–26. PLL Input Reference Clocks in Transceiver Operation for F484 and Larger Packages (1), (2), (3)



Notes to Figure 1–26:

(1) The REFCLK2 and REFCLK3 pins are dual-purpose CLKIO, REFCLK, or DIFFCLK pins that reside in banks 3A and 8A respectively.

(2) The REFCLK[1..0] and REFCLK[5..4] pins are dual-purpose differential REFCLK or DIFFCLK pins that reside in banks 3B and 8B respectively. These clock input pins do not have access to the clock control blocks and GCLK networks. For more details, refer to the *Clock Networks and PLLs in Cyclone IV Devices* chapter.

(3) Using any clock input pins other than the designated REFCLK pins as shown here to drive the MPLLs and GPLLs may have reduced jitter performance.

The input reference clocks reside in banks 3A, 3B, 8A, and 8B have dedicated $V_{CC\_CLKIN3A}$, $V_{CC\_CLKIN3B}$, $V_{CC\_CLKIN8A}$, and $V_{CC\_CLKIN8B}$ power supplies separately in their respective I/O banks to avoid the different power level requirements in the same bank for general purpose I/Os (GPIOs). Table 1–6 lists the supported I/O standard for the REFCLK pins.

Table 1–6. REFCLK I/O Standard Support

I/O Standard	HSSI Protocol	Coupling	Termination	VCC_CLKIN Level		I/O Pin Type		
				Input	Output	Column I/O	Row I/O	Supported Banks
LVDS	ALL	Differential AC (Needs off-chip resistor to restore V_{CM})	Off-chip	2.5 V	Not Supported	Yes	No	3A, 3B, 8A, 8B
LVPECL	ALL		Off-chip	2.5 V	Not Supported	Yes	No	3A, 3B, 8A, 8B
1.2 V, 1.5 V, 3.3 V PCML	ALL		Off-chip	2.5 V	Not Supported	Yes	No	3A, 3B, 8A, 8B
	ALL		Off-chip	2.5 V	Not Supported	Yes	No	3A, 3B, 8A, 8B
	ALL		Off-chip	2.5 V	Not Supported	Yes	No	3A, 3B, 8A, 8B
HCSL	PCIe	Differential DC	Off-chip	2.5 V	Not Supported	Yes	No	3A, 3B, 8A, 8B

Table 1–9 lists the high- and low-speed clock sources for each channel.

Table 1–9. High- and Low-Speed Clock Sources for Each Channel in Non-Bonded Channel Configuration

Package	Transceiver Block	Transceiver Channel	High- and Low-Speed Clocks Sources	
			Option 1	Option 2
F324 and smaller	GXBL0	All channels	MPLL_1	MPLL_2
F484 and larger	GXBL0	Channels 0, 1	MPLL_5/GPLL_1	MPLL_6
		Channels 2, 3	MPLL_5	MPLL_6/MPLL_7 (1)
	GXBL1 (1)	Channels 0, 1	MPLL_7/MPLL_6	MPLL_8
		Channels 2, 3	MPLL_7	MPLL_8/GPLL_2

Note to Table 1–9:

(1) MPLL_7 and GXBL1 are not applicable for transceivers in F484 package

Table 1–13. Automatic RX Phase Compensation FIFO Read Clock Selection (Part 2 of 2)

Channel Configuration		Quartus II Selection
Bonded	With rate match FIFO (1)	`coreclkout` clock feeds the FIFO read clock for the bonded channels. `coreclkout` clock is the common bonded low-speed clock, which also feeds the FIFO read clock and transmitter PCS in the bonded channels.
	Without rate match FIFO	`rx_clkout` clock feeds the FIFO read clock. `rx_clkout` is forwarded through the receiver channel from low-speed recovered clock, which also feeds the FIFO write clock.

Note to Table 1–13:

(1) Configuration with rate match FIFO is supported in transmitter and receiver operation.

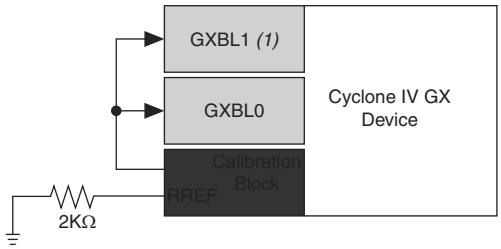
When using user-specified clock option, ensure that the clock feeding `rx_coreclk` port has 0 ppm difference with the RX phase compensation FIFO write clock.

Calibration Block

This block calibrates the OCT resistors and the analog portions of the transceiver blocks to ensure that the functionality is independent of process, voltage, and temperature (PVT) variations.

Figure 1–40 shows the location of the calibration block and how it is connected to the transceiver blocks.

Figure 1–40. Transceiver Calibration Blocks Location and Connection

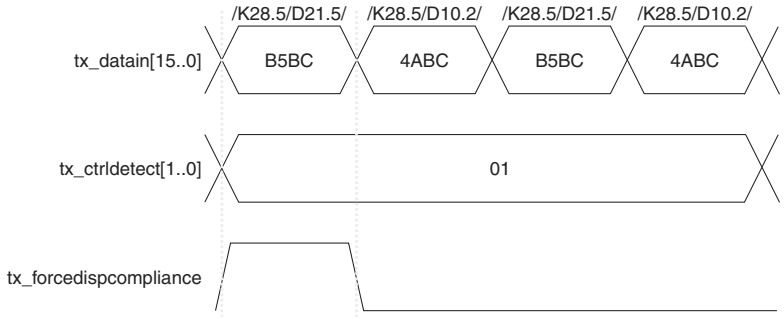


Note to Figure 1–40:

(1) Transceiver block GXBL1 is only available for devices in F484 and larger packages.

The compliance pattern is a repeating sequence of the four code groups: /K28.5/; /D21.5/; /K28.5/; /D10.2/. Figure 1–53 shows the compliance pattern transmission where the `tx_forcedispcompliance` port must be asserted in the same parallel clock cycle as /K28.5/D21.5/ of the compliance pattern on `tx_datain[15..0]` port.

Figure 1–53. Compliance Pattern Transmission Support in PCI Express (PIPE) Mode



Reset Requirement

Cyclone IV GX devices meets the PCIe reset time requirement from device power up to the link active state with the configuration schemes listed in Table 1–17.

Table 1–18. Electrical Idle Inference Conditions

Device	Configuration Scheme	Configuration Time (ms)
EP4CGX15	Passive serial (PS)	51
EP4CGX22	PS	92
EP4CGX30 (1)	PS	92
EP4CGX50	Fast passive parallel (FPP)	41
EP4CGX75	FPP	41
EP4CGX110	FPP	70
EP4CGX150	FPP	70

Note to Table 1–18:

(1) EP4CGX30 device in F484 package fulfills the PCIe reset time requirement using FPP configuration scheme with configuration time of 41 ms.

GIGE Mode

GIGE mode provides the transceiver channel datapath configuration for GbE (specifically the 1000 Base-X physical layer device (PHY) standard) protocol implementation. The Cyclone IV GX transceiver provides the PMA and the following PCS functions as defined in the IEEE 802.3 specification for 1000 Base-X PHY:

- 8B/10B encoding and decoding
- synchronization

If you enabled the auto-negotiation state machine in the FPGA core with the rate match FIFO, refer to “Clock Frequency Compensation” on page 1–63.

There are three methods that you can use to dynamically reconfigure the PMA controls of a transceiver channel:

- "Method 1: Using logical_channel_address to Reconfigure Specific Transceiver Channels" on page 3–14
- "Method 2: Writing the Same Control Signals to Control All the Transceiver Channels" on page 3–16
- "Method 3: Writing Different Control Signals for all the Transceiver Channels at the Same Time" on page 3–19

Method 1: Using logical_channel_address to Reconfigure Specific Transceiver Channels

Enable the `logical_channel_address` port by selecting the **Use 'logical_channel_address' port** option on the **Analog controls** tab. This method is applicable only for a design where the dynamic reconfiguration controller controls more than one channel.

You can additionally reconfigure either the receiver portion, transmitter portion, or both the receiver and transmitter portions of the transceiver channel by setting the corresponding value on the `rx_tx_duplex_sel` input port. For more information, refer to Table 3–2 on page 3–4.

Connecting the PMA Control Ports

The selected PMA control ports remain fixed in width, regardless of the number of channels controlled by the ALTGX_RECONFIG instance:

- `tx_vodctrl` and `tx_vodctrl_out` are fixed to 3 bits
- `tx_preemp` and `tx_preemp_out` are fixed to 5 bits
- `rx_eqdcgain` and `rx_eqdcgain_out` are fixed to 2 bits
- `rx_eqctrl` and `rx_eqctrl_out` are fixed to 4 bits

Write Transaction

To complete a write transaction, perform the following steps:

1. Set the selected PMA control ports to the desired settings (for example, `tx_vodctrl` = **3'b001**).
2. Set the `logical_channel_address` input port to the logical channel address of the transceiver channel whose PMA controls you want to reconfigure.
3. Set the `rx_tx_duplex_sel` port to **2'b10** so that only the transmit PMA controls are written to the transceiver channel.
4. Ensure that the `busy` signal is low before you start a write transaction.
5. Assert the `write_all` signal for one `reconfig_clk` clock cycle.

The `busy` output status signal is asserted high to indicate that the dynamic reconfiguration controller is busy writing the PMA control values. When the write transaction has completed, the `busy` signal goes low.

Method 3: Writing Different Control Signals for all the Transceiver Channels at the Same Time

If you disable the **Use the same control signal for all the channels** option, the PMA control ports for a write transaction are separate for each channel. If you disable this option, the width of the PMA control ports are fixed as follows:

PMA Control Ports Used in a Write Transaction

- `tx_vodctrl` is 3 bits per channel
- `tx_preemp` are 5 bits per channel
- `rx_eqdcgain` is 2 bits per channel
- `rx_eqctrl` is 4 bits per channel

For example, if you have two channels, the `tx_vodctrl` is 6 bits wide (`tx_vodctrl [2:0]` corresponds to channel 1 and `tx_vodctrl [5:3]` corresponds to channel 2).

PMA Control Ports Used in a Read Transaction

The width of the PMA control ports for a read transaction are always separate for each channel as explained in "Method 2: Writing the Same Control Signals to Control All the Transceiver Channels" on page 3–16.

Write Transaction

Because the PMA controls of all the channels are written, if you want to reconfigure a specific channel connected to the ALTGX_RECONFIG instance, set the new value at the corresponding PMA control port of the channel under consideration and retain the previously stored values in the other active channels with a read transaction prior to this write transaction.

For example, if the number of channels controlled by the ALTGX_RECONFIG instance is two, the `tx_vodctrl` signal in this case would be 6 bits wide. The `tx_vodctrl[2:0]` signal corresponds to channel 1 and the `tx_vodctrl[5:3]` signal corresponds to channel 2.

- To dynamically reconfigure the PMA controls of only channel 2 with a new value, first perform a read transaction to retrieve the existing PMA control values from `tx_vodctrl_out[5:0]`. Use the `tx_vodctrl_out[2:0]` value for `tx_vodctrl[2:0]` to write in channel 1. By doing so, channel 1 is overwritten with the same value.
- Perform a write transaction. This ensures that the new values are written only to channel 2 while channel 1 remains unchanged.

Functional Simulation of the Dynamic Reconfiguration Process

This section describes the points to be considered during functional simulation of the dynamic reconfiguration process.

- You must connect the ALTGX_RECONFIG instance to the ALTGX_instance/ALTGX instances in your design for functional simulation.
- The functional simulation uses a reduced timing model of the dynamic reconfiguration controller. The duration of the offset cancellation process is 16 `reconfig_clk` clock cycles for functional simulation only.
- The `gxb_powerdown` signal must not be asserted during the offset cancellation sequence (for functional simulation and silicon).

Document Revision History

Table 3–8 lists the revision history for this chapter.

Table 3–8. Document Revision History

Date	Version	Changes
November 2011	2.1	■ Updated "Dynamic Reconfiguration Controller Architecture", "PMA Controls Reconfiguration Mode", "PLL Reconfiguration Mode", and "Error Indication During Dynamic Reconfiguration" sections. ■ Updated Table 3–2 and Table 3–4.
December 2010	2.0	■ Updated for the Quartus II software version 10.1 release. ■ Updated Table 3–1, Table 3–2, Table 3–3, Table 3–4, Table 3–5, and Table 3–6. ■ Added Table 3–7. ■ Updated Figure 3–1, Figure 3–11, Figure 3–13, and Figure 3–14. ■ Updated "Offset Cancellation Feature", "Error Indication During Dynamic Reconfiguration", "Data Rate Reconfiguration Mode Using RX Local Divider", "PMA Controls Reconfiguration Mode", and "Control and Status Signals for Channel Reconfiguration" sections.
July 2010	1.0	Initial release.

DC Characteristics

This section lists the I/O leakage current, pin capacitance, on-chip termination (OCT) tolerance, and bus hold specifications for Cyclone IV devices.

Supply Current

The device supply current requirement is the minimum current drawn from the power supply pins that can be used as a reference for power size planning. Use the Excel-based early power estimator (EPE) to get the supply current estimates for your design because these currents vary greatly with the resources used. Table 1–6 lists the I/O pin leakage current for Cyclone IV devices.

Table 1–6. I/O Pin Leakage Current for Cyclone IV Devices *(1), (2)*

Symbol	Parameter	Conditions	Device	Min	Typ	Max	Unit
I_I	Input pin leakage current	V_I = 0 V to $V_{CCIOMAX}$	—	–10	—	10	µA
I_{OZ}	Tristated I/O pin leakage current	V_O = 0 V to $V_{CCIOMAX}$	—	–10	—	10	µA

Notes to Table 1–6:

(1) This value is specified for normal device operation. The value varies during device power-up. This applies for all V_{CCIO} settings (3.3, 3.0, 2.5, 1.8, 1.5, and 1.2 V).

(2) The 10 µA I/O leakage current limit is applicable when the internal clamping diode is off. A higher current can be observed when the diode is on.

Bus Hold

The bus hold retains the last valid logic state after the source driving it either enters the high impedance state or is removed. Each I/O pin has an option to enable bus hold in user mode. Bus hold is always disabled in configuration mode.

Table 1–7 lists bus hold specifications for Cyclone IV devices.

Table 1–7. Bus Hold Parameter for Cyclone IV Devices (Part 1 of 2) *(1)*

Parameter	Condition	V_{CCIO} (V)												Unit
		1.2		1.5		1.8		2.5		3.0		3.3		
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Bus hold low, sustaining current	$V_{IN} > V_{IL}$ (maximum)	8	—	12	—	30	—	50	—	70	—	70	—	µA
Bus hold high, sustaining current	$V_{IN} < V_{IL}$ (minimum)	–8	—	–12	—	–30	—	–50	—	–70	—	–70	—	µA
Bus hold low, overdrive current	0 V < V_{IN} < V_{CCIO}	—	125	—	175	—	200	—	300	—	500	—	500	µA
Bus hold high, overdrive current	0 V < V_{IN} < V_{CCIO}	—	–125	—	–175	—	–200	—	–300	—	–500	—	–500	µA

f For more information about receiver input and transmitter output waveforms, and for other differential I/O standards, refer to the I/O Features in Cyclone IV Devices chapter.

Table 1–18. Differential SSTL I/O Standard Specifications for Cyclone IV Devices (1)

I/O Standard	V_{CCIO} (V)			$V_{Swing(DC)}$ (V)		$V_{X(AC)}$ (V)			$V_{Swing(AC)}$ (V)		$V_{OX(AC)}$ (V)		
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Max	Min	Typ	Max
SSTL-2 Class I, II	2.375	2.5	2.625	0.36	V_{CCIO}	$V_{CCIO}/2 - 0.2$	—	$V_{CCIO}/2 + 0.2$	0.7	V_{CCIO}	$V_{CCIO}/2 - 0.125$	—	$V_{CCIO}/2 + 0.125$
SSTL-18 Class I, II	1.7	1.8	1.90	0.25	V_{CCIO}	$V_{CCIO}/2 - 0.175$	—	$V_{CCIO}/2 + 0.175$	0.5	V_{CCIO}	$V_{CCIO}/2 - 0.125$	—	$V_{CCIO}/2 + 0.125$

Note to Table 1–18:

(1) Differential SSTL requires a V_{REF} input.

Table 1–19. Differential HSTL I/O Standard Specifications for Cyclone IV Devices (1)

I/O Standard	V_{CCIO} (V)			$V_{DIF(DC)}$ (V)		$V_{X(AC)}$ (V)			$V_{CM(DC)}$ (V)			$V_{DIF(AC)}$ (V)	
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Typ	Max	Min	Max
HSTL-18 Class I, II	1.71	1.8	1.89	0.2	—	0.85	—	0.95	0.85	—	0.95	0.4	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.2	—	0.71	—	0.79	0.71	—	0.79	0.4	—
HSTL-12 Class I, II	1.14	1.2	1.26	0.16	V_{CCIO}	$0.48 \times V_{CCIO}$	—	$0.52 \times V_{CCIO}$	$0.48 \times V_{CCIO}$	—	$0.52 \times V_{CCIO}$	0.3	$0.48 \times V_{CCIO}$

Note to Table 1–19:

(1) Differential HSTL requires a V_{REF} input.

Table 1–20. Differential I/O Standard Specifications for Cyclone IV Devices (1) (Part 1 of 2)

I/O Standard	V_{CCIO} (V)			V_{ID} (mV)		V_{ICM} (V) (2)			V_{OD} (mV) (3)			V_{OS} (V) (3)		
	Min	Typ	Max	Min	Max	Min	Condition	Max	Min	Typ	Max	Min	Typ	Max
LVPECL (Row I/Os) (6)	2.375	2.5	2.625	100	—	0.05	$D_{MAX} \leq 500$ Mbps	1.80	—	—	—	—	—	—
						0.55	500 Mbps $\leq D_{MAX} \leq$ 700 Mbps	1.80						
						1.05	$D_{MAX} >$ 700 Mbps	1.55						
LVPECL (Column I/Os) (6)	2.375	2.5	2.625	100	—	0.05	$D_{MAX} \leq$ 500 Mbps	1.80	—	—	—	—	—	—
						0.55	500 Mbps $\leq D_{MAX} \leq$ 700 Mbps	1.80						
						1.05	$D_{MAX} >$ 700 Mbps	1.55						
LVDS (Row I/Os)	2.375	2.5	2.625	100	—	0.05	$D_{MAX} \leq$ 500 Mbps	1.80	247	—	600	1.125	1.25	1.375
						0.55	500 Mbps $\leq D_{MAX} \leq$ 700 Mbps	1.80						
						1.05	$D_{MAX} >$ 700 Mbps	1.55						